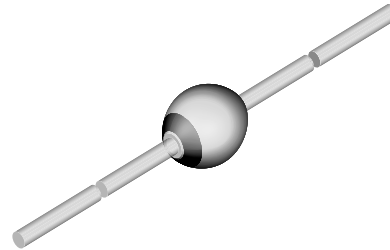


Ultra Fast Avalanche Sinterglass Diode

Features

- Glass passivated junction
- Hermetically sealed package
- Very low switching losses
- Low reverse current
- High reverse voltage
- Lead (Pb)-free component
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



949539

Applications

Switched mode power supplies
High-frequency inverter circuits

Terminals: Plated axial leads, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any

Weight: approx. 369 mg

Mechanical Data

Case: SOD-57 Sintered glass case

Parts Table

Part	Type differentiation	Package
BYV26A	$V_R = 200 \text{ V}; I_{FAV} = 1 \text{ A}$	SOD-57
BYV26B	$V_R = 400 \text{ V}; I_{FAV} = 1 \text{ A}$	SOD-57
BYV26C	$V_R = 600 \text{ V}; I_{FAV} = 1 \text{ A}$	SOD-57
BYV26D	$V_R = 800 \text{ V}; I_{FAV} = 1 \text{ A}$	SOD-57
BYV26E	$V_R = 1000 \text{ V}; I_{FAV} = 1 \text{ A}$	SOD-57

Absolute Maximum Ratings

$T_{amb} = 25 \text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Test condition	Part	Symbol	Value	Unit
Reverse voltage = Repetitive peak reverse voltage	see electrical characteristics	BYV26A	$V_R = V_{RRM}$	200	V
		BYV26B	$V_R = V_{RRM}$	400	V
		BYV26C	$V_R = V_{RRM}$	600	V
		BYV26D	$V_R = V_{RRM}$	800	V
		BYV26E	$V_R = V_{RRM}$	1000	V
Peak forward surge current	$t_p = 10 \text{ ms}$, half sinewave		I_{FSM}	30	A
Average forward current			I_{FAV}	1	A
Non repetitive reverse avalanche energy	$I_{(BR)R} = 1 \text{ A}$, inductive load		E_R	10	mJ
Junction and storage temperature range			$T_j = T_{stg}$	- 55 to + 175	$^\circ\text{C}$

Maximum Thermal Resistance

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Test condition	Symbol	Value	Unit
Junction ambient	$l = 10\text{ mm}$, $T_L = \text{constant}$	R_{thJA}	45	K/W

Electrical Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Test condition	Part	Symbol	Min	Typ.	Max	Unit
Forward voltage	$I_F = 1\text{ A}$		V_F			2.5	V
	$I_F = 1\text{ A}$, $T_J = 175\text{ }^{\circ}\text{C}$		V_F			1.3	V
Reverse current	$V_R = V_{RRM}$		I_R			5	μA
	$V_R = V_{RRM}$, $T_J = 150\text{ }^{\circ}\text{C}$		I_R			100	μA
Reverse breakdown voltage	$I_R = 100\text{ }\mu\text{A}$	BYV26A	$V_{(BR)R}$	300			V
		BYV26B	$V_{(BR)R}$	500			V
		BYV26C	$V_{(BR)R}$	700			V
		BYV26D	$V_{(BR)R}$	900			V
		BYV26E	$V_{(BR)R}$	1100			V
Reverse recovery time	$I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $i_R = 0.25\text{ A}$	BYV26A-BYV26C	t_{rr}			30	ns
		BYV26D-BYV26E	t_{rr}			75	ns

Typical Characteristics ($T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

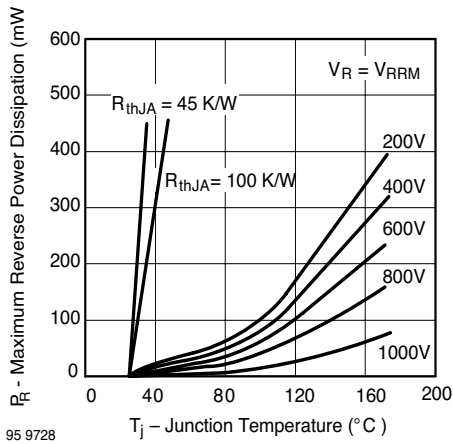


Figure 1. Max. Reverse Power Dissipation vs. Junction Temperature

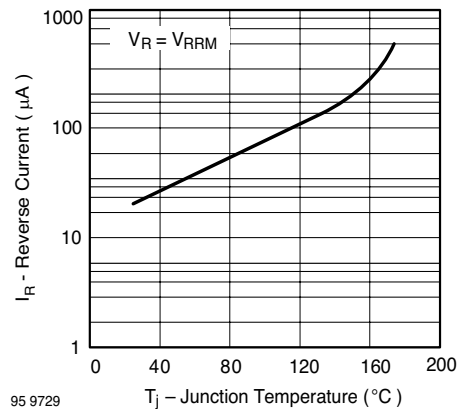


Figure 2. Max. Reverse Current vs. Junction Temperature

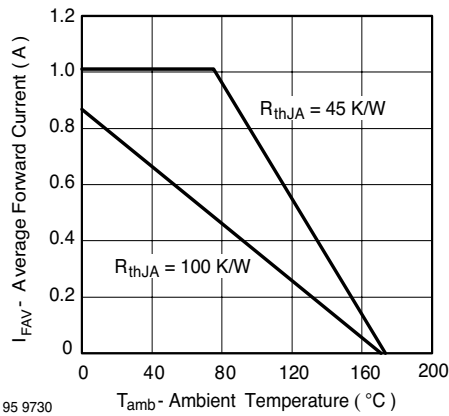


Figure 3. Max. Average Forward Current vs. Ambient Temperature

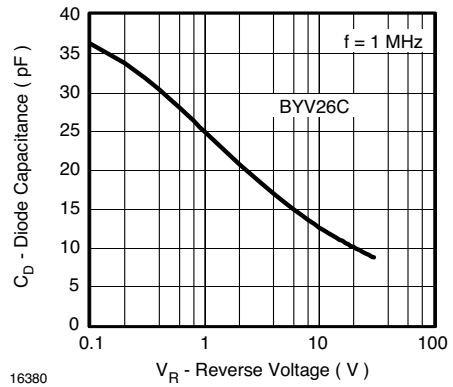


Figure 5. Diode Capacitance vs. Reverse Voltage

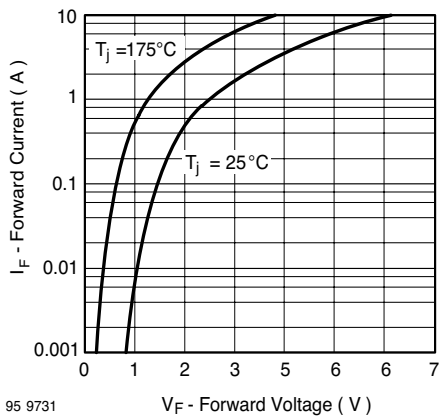


Figure 4. Max. Forward Current vs. Forward Voltage

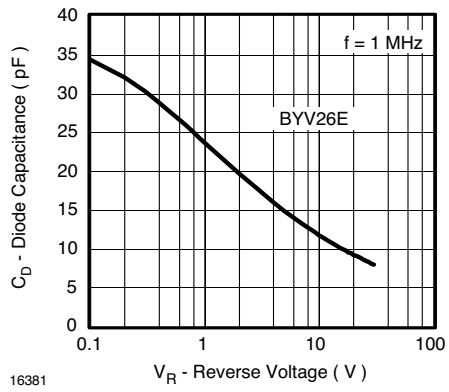


Figure 6. Diode Capacitance vs. Reverse Voltage

Package Dimensions in mm (Inches)

